

(1,00mm) .03937"

MEC1 SERIES

MEC1-120-02-F-D-A

MEC1-130-02-F-D-A

MEC1-140-02-L-D

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over 50µ"

(1,27µm) Ni

Operating Temp Range:

-55°C to +125°C

Current Rating:

2A @ 80°C ambient

(See website for details)

Voltage Rating:

300 VAC

Insertion Depth:

(5,84mm) .230" to

(8,13mm) .320"

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

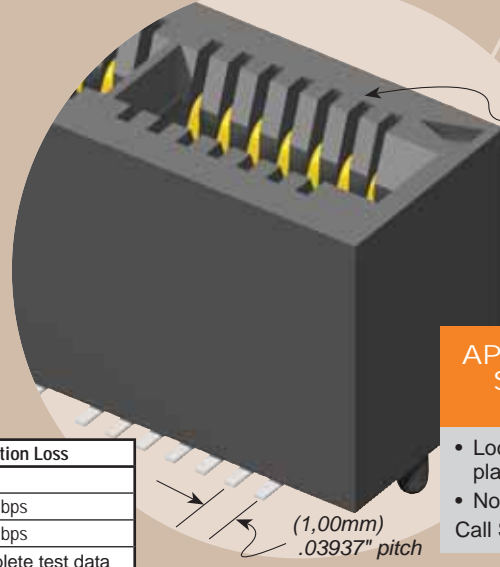
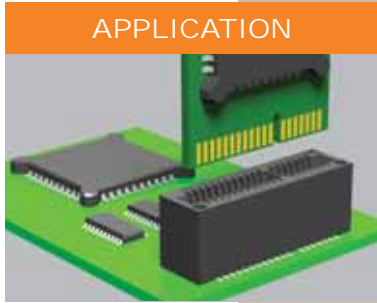
(0,10mm) .004" max (05-20)

(0,15mm) .006" max (30-70)



Mates with:
(1,60mm) .062" card

APPLICATION



Mates with
(1,60mm)
.062" card

APPLICATION SPECIFIC OPTION

- Locking Clip (Manual placement required).
- Non-polarized Call Samtec.

1mm MEC1	Rated @ -3dB Insertion Loss
9,19mm Stack Height	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com

MEC1

1

POSITIONS PER ROW

02

PLATING OPTION

D

OTHER OPTION

05, 08, 20, 30, 40, 50, 60, 70

-F

= Gold flash on contact, Matte tin on tail

-L

= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

-A

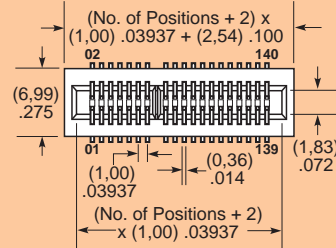
= Alignment Pin metal or plastic at Samtec discretion.

-K

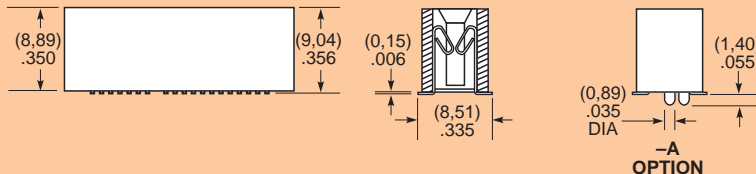
= (7,87mm) .310" DIA Polyimide film Pick & Place Pad

-TR

= Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116



Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM